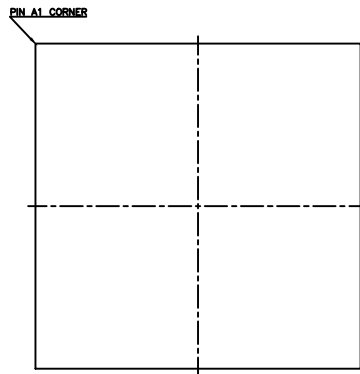
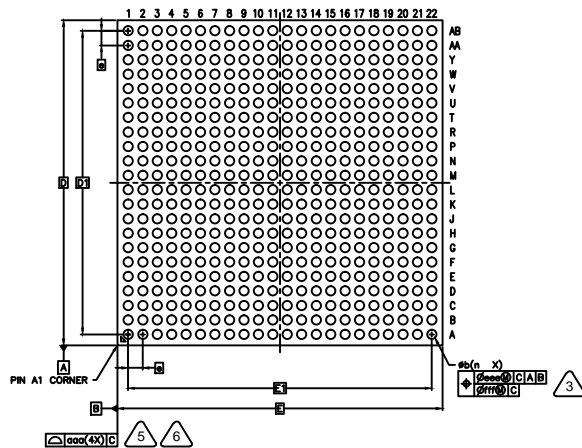
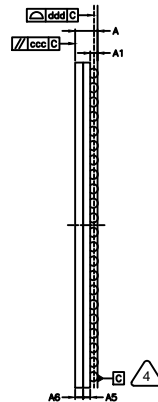




TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Package:		MFC LFBGA		
Body Size:	X E Y D	18,000	BSC	
Ball Pitch:	e	0.800		
Total Thickness:	A	1.123	1.238	1.353
Mold Cap Thickness:	A6	0.450	Ref.	
Substrate Thickness:	A5	0.388	Ref.	
Ball Diameter:		0.500		
Stand Off:	A1	0.300	0.400	0.500
Ball Width:	b	0.450	0.500	0.550
Package Edge Tolerance:	aaa	0.150		
Mold Parallelism:	ccc	0.200		
Coplanarity:	ddd	0.200		
Ball Offset (Package):	eee	0.150		
Ball Offset (Ball):	fff	0.080		
Ball Count:	n	484		
Edge Ball Center to Center:	X E1 Y D1	16.800		

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square
- PRIMARY DATUM \square AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.5

Title: Package Outline Drawing

Pkg Type: FCCSP

Document No:

Product Family: LN2-CT-20

PKG I/O Count: 484

POD-240068

Product Name: LN2-CT-20-CBG484

Pkg Size: 18x18 mm

Rev: A

Disclaimers

Lattice makes no warranty, representation, or guarantee regarding the accuracy of information contained in this document or the suitability of its products for any particular purpose. All information herein is provided AS IS, with all faults, and all associated risk is the responsibility entirely of the Buyer. The information provided herein is for informational purposes only and may contain technical inaccuracies or omissions, and may be otherwise rendered inaccurate for many reasons, and Lattice assumes no obligation to update or otherwise correct or revise this information. Products sold by Lattice have been subject to limited testing and it is the Buyer's responsibility to independently determine the suitability of any products and to test and verify the same. LATTICE PRODUCTS AND SERVICES ARE NOT DESIGNED, MANUFACTURED, OR TESTED FOR USE IN LIFE OR SAFETY CRITICAL SYSTEMS, HAZARDOUS ENVIRONMENTS, OR ANY OTHER ENVIRONMENT REQUIRING FAIL-SAFE PERFORMANCE, INCLUDING ANY APPLICATION IN WHICH THE FAILURE OF THE PRODUCT OR SERVICE COULD LEAD TO DEATH, PERSONAL INJURY, SEVERE PROPERTY DAMAGE OR ENVIRONMENTAL HARM (COLLECTIVELY, "HIGH-RISK USES"). FURTHER, BUYER MUST TAKE PRUDENT STEPS TO PROTECT AGAINST PRODUCT AND SERVICE FAILURES, INCLUDING PROVIDING APPROPRIATE REDUNDANCIES, FAIL-SAFE FEATURES, AND/OR SHUT-DOWN MECHANISMS. LATTICE EXPRESSLY DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY OF FITNESS OF THE PRODUCTS OR SERVICES FOR HIGH-RISK USES.

The information provided in this document is proprietary to Lattice Semiconductor, and Lattice reserves the right to make any changes to the information in this document or to any products at any time without notice.